

PATENT ASSIGNMENT

Electronic Version v1.1
Stylesheet Version v1.1

SUBMISSION TYPE:

NEW ASSIGNMENT

NATURE OF CONVEYANCE:

ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Nuvotronics, LLC	08/31/2010

RECEIVING PARTY DATA

Name:	IP Cube Partners Co. Ltd.
Street Address:	2804 S-Trenue, 26 Yeouido-dong, Yeongdeungpo-gu
City:	Seoul
State/Country:	REPUBLIC OF KOREA
Postal Code:	150-879

PROPERTY NUMBERS Total: 10

Property Type	Number
Patent Number:	6782182
Patent Number:	6799897
Patent Number:	6810162
Patent Number:	6811853
Patent Number:	6819858
Patent Number:	6826324
Patent Number:	6827503
Patent Number:	6839474
Patent Number:	6842552
Patent Number:	6847764

CORRESPONDENCE DATA

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CH \$400.00 6782182

501466089

PATENT
REEL: 025950 FRAME: 0153

Correspondent Name: Michael I. Angert
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Address Line 4: Washington, DISTRICT OF COLUMBIA 20006

ATTORNEY DOCKET NUMBER:	TEN 32615 CASES
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NAME OF SUBMITTER:	Michael I. Angert
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Total Attachments: 23

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ASSIGNMENT OF PATENT RIGHTS

WHEREAS, Nuvotronics, LLC, a company formed under the laws of the Commonwealth of Virginia (hereinafter "Seller"), is the owner of rights to the patents listed on *Exhibit A* attached hereto (the "Patents").

WHEREAS, IP Cube Partners Co. Ltd., a company formed under the laws of the Republic of Korea (hereinafter "Purchaser"), is acquiring Seller's entire right, title, and interest in, to, and under said Patents, as well as their foreign counterparts, under the terms of a Patent Purchase Agreement (the "Agreement").

NOW THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, Seller does hereby sell, assign, transfer, and set over to Purchaser, Seller's entire right, title, and ownership interest in the Patents, and any inventions and discoveries claimed in said Patents, any continuations, continuations-in-part, divisions, extensions, amendments, conversions, renewals, restorations, or any reissue or reissues of said Patents already granted and which may be granted, any certificates of reexamination already granted and which may be granted, the same to be held and enjoyed by Purchaser for its own use and enjoyment, and for the use and enjoyment of its successors, assigns, or other legal representatives, to the end of the term or terms for which said Patents are or may be granted, reissued, or extended as fully and entirely as the same would have been held and enjoyed by Seller if this assignment and sale had not been made; together with all claims for damages by reason of past infringement of said Patents, with the right to sue for, and collect the same for its own use and behalf, and for the use and behalf of its successors, assigns, or other legal representatives.

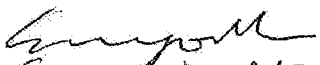
And, Seller hereby authorizes and requests the Commissioner of Patents and Trademarks to issue any and all Letters Patents of the United States on said inventions to Purchaser as assignee of Seller's entire right, title, and interest, and hereby covenants that Seller has full right to convey Seller's entire interest herein assigned, and that Seller has not executed, and will not execute, any agreements in conflict therewith.

IN WITNESS WHEREOF, the parties, by their duly authorized representatives, have executed this Assignment.

NUVOTRONICS, LLC

By: 
Name: David W. Sherer
Title: President
Date: 8-31-2010

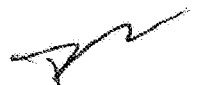
IP CUBE PARTNERS CO. LTD.

By: 
Name: Seungbok Min
Title: CEO
Date: Aug 31 2010


G. Min

EXHIBIT A

List of Patents



G. m

Country	Application Number	Patent Number	Title of Invention	Status
US	60/205,973		Optical filters made from vertical etched silicon layers on <110> wafer	Expired
US	09/862,037	6768590	Method of fabricating optical filters	Issued
US	10/871,689	7267781	Method of fabricating optical filters	Issued
US	11/891,059		Method of fabricating optical filters	Abandoned
US	09/199,545		Optoelectronic Component	Abandoned
US	09/574,482		Optoelectronic device-optical fiber connector having micromachined pit for passive alignment of the optoelectronic device	Abandoned
US	11/124,775	7208725	Optoelectronic component with encapsulant	Issued
US	11/139,270	7288756	Optoelectronic component having passively aligned optoelectronic device	Issued
US	11/220,884	7355166	Optoelectronic component having electrical connection and formation method thereof	Issued
US	11/223,402	7348550	Optoelectronic component with front to side surface electrical conductor	Issued
US	11/223,403	7288758	Wafer-level optoelectronic device substrate	Issued
US	11/506,250	7291833	Optoelectronic component	Issued

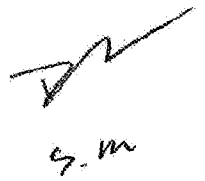


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Country	Application Number	Patent Number	Title of Invention	Status
US	12/079,248		OPTOELECTRONIC COMPONENT COMPRISING AN ENCAPSULANT	Issuing
US	10/192,752		Optoelectronic device-optical fiber connector having micromachined pit for passive alignment of the optoelectronic device	Abandoned
US	12/837,734		Optoelectronic device-optical fiber connector having micromachined pit for passive alignment of the optoelectronic device	Pending
US	09/560,418	6501619	Inductive magnetic recording head having inclined magnetic read/write pole and method of making same	Issued
US	60/197,129		Fiber optic pressure sensor	Expired
US	09/814,526	6738145	Micromachined, etalon-based optical fiber pressure sensor	Issued
US	09/519,165	6811853	Single mask lithographic process for patterning multiple types of surface features	Issued
	60/217,259		Optical fiber array for preventing flow of glue between fibers and waveguide	Expired
US	09/713,117	6526204	Optical fiber array for preventing flow of glue between fibers and waveguide	Issued
US	60/195,636		Optical Fiber Array	Expired

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Country	Application Number	Patent Number	Title of Invention	Status
US	09/614,155	6866426	Open face optical fiber array for coupling to integrated optic waveguides and optoelectronic submounts	Issued
US	09/827,183	6848839	Methods and devices for coupling optoelectronic packages	Issued
US	60/195,254		Optoelectronic package	Expired
US	09/825,205	6595700	Optoelectronic packages having insulation layers	Issued
US	60/197,130		Connector structure for integrated optic devices	Expired
US	09/835,863	6847764	Optical interconnect having alignment depression	Issued
US	60/197,154		Fiber array switch with micromachined front face	Expired
US	60/201,347		Fiber array switches and alternative embodiments	Expired
US	09/835,106	6826324	Optical waveguide switch	Issued
US	10/356,663	6842552	Optical waveguide switch	Issued



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Country	Application Number	Patent Number	Title of Invention	Status
US	09/728,896	6,832,016	FIBER ARRAY SWITCH HAVING MICROMACHINED FRONT FACE WITH ROLLER BALLS	Expired
US	09/728,895		FIBER ARRAY SWITCH HAVING MICROMACHINED FRONT FACE WITH ROLLER BALLS	Abandoned
US	60/201,352		Optical waveguide switch having stepped waveguide holding member	Expired
US	09/845,773	6633691	Optical waveguide switch having stepped waveguide holding member	Issued
US	60/201,348		Single mask technique for making positive and negative micromachined features on a substrate	Expired
US	09/847,798	6627096	Single mask technique for making positive and negative micromachined features on a substrate	Issued
US	60/204,473		Single mask process for patterning integrated optic waveguides, metallizations and micromachined features	Expired


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Country	Application Number	Patent Number	Title of Invention	Status
US	60/206,485		Single mask method for making integrated optic waveguides and micromachined features	Expired
US	60/257,021		alternative embodiments for making the multilevel contact mask	Expired
US	60/202,596		Multilevel contact mask for patterning multilevel substrates	Expired
US	09/862,593	6,756,185	METHOD FOR MAKING INTEGRATED OPTICAL WAVEGUIDES AND MICROMACHINED FEATURES	Issued
US	09/853,250		Multi-level lithography masks	Abandoned
US	09/858,999	7255978	Multi-level optical structure and method of manufacture	Issued
US	11/891,721		Multi-level optical structure and method of manufacture	Pending

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Country	Application Number	Patent Number	Title of Invention	Status
US	60/221,217		Method for making 3-D structures by etching mask with graded composition	Expired
US	09/911,834	6613243	Method of making a 3-D structure using an erodable mask formed from a film having a composition that varies in its direction of thickness	Issued
US	60/243,446		Fiber array with V-groove chip and mount	Expired
US	10/037,971	6819858	Fiber array with V-groove chip and mount	Issued
US	60/243,445		Single mask process for patterning gray scale features and micromachined features	Expired
US	09/999,332	6759173	Single mask process for patterning microchip having grayscale and micromachined features	Issued
US	60/243,172		Wafer-level packaging for optoelectronic devices	Expired
US	09/999,517	7345316	Wafer level packaging for optoelectronic devices	Issued
US	11/503,023		Optical device package	Pending

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Country	Application Number	Patent Number	Title of Invention	Status
US	60/249,792		Grin lens array for coupling to integrated optical devices	Expired
US	09/988,055	6898029	Optical bench with alignment subassembly	Issued
US	11/136,090		Optical bench with alignment subassembly	Abandoned
US	60/249,794		Silicon package for optoelectronic devices	Expired
US	09/966,973	6932519	Optical device package	Issued
US	11/080,002	7246953	Optical device package	Issued
US	11/209,355		Optical device package	Abandoned
US	60/249,795		Grin lens array for coupling to integrated optical devices	Expired
US	09/987,766	6839474	Optical assembly for coupling with integrated optical devices and method for making	Issued
US	60/249,806		'M' style connector having spheres	Expired
US	10/054,575	6799897	Optical connector system	Issued
US	60/249,793		Tapered waveguide with graded composition for mode-matching	Expired

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Country	Application Number	Patent Number	Title of Invention	Status
US	60/243,444		Tapered waveguide for mode-matching	Expired
US	09/983,984	7068870	Variable width waveguide for mode-matching and method for making	Issued
US	60/250,943		Optoelectronic package having bumped preform	Expired
US	09/990,509	6827503	Optical device package having a configured frame	Issued
US	60/287,032		Optical waveguide termination with vertical and horizontal mode shaping	Expired
US	60/255,868		Optical waveguide termination with vertical and horizontal mode shaping	Expired
PCT	PCT/US01/51497		OPTICAL WAVEGUIDE TERMINATION WITH VERTICAL AND HORIZONTAL MODE SHAPING	Expired
US	10/450,475	6987919	Optical waveguide termination with vertical and horizontal mode shaping	Issued
EU	1273979.3	1356327	OPTICAL WAVEGUIDE TERMINATION WITH VERTICAL AND HORIZONTAL MODE SHAPING	Issued

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Country	Application Number	Patent Number	Title of Invention	Status
FR	1273979.3	1356327	OPTICAL WAVEGUIDE TERMINATION WITH VERTICAL AND HORIZONTAL MODE SHAPING	Issued
DE	1273979.3	1356327	OPTICAL WAVEGUIDE TERMINATION WITH VERTICAL AND HORIZONTAL MODE SHAPING	Issued
IT	1273979.3	1356327	OPTICAL WAVEGUIDE TERMINATION WITH VERTICAL AND HORIZONTAL MODE SHAPING	Issued
UK	1273979.3	1356327	OPTICAL WAVEGUIDE TERMINATION WITH VERTICAL AND HORIZONTAL MODE SHAPING	Issued
US	60/255,865		Optoelectronic package with stepped via-structure	Expired
US	10/013,084	6883977	Optical device package for flip-chip mounting	Issued
US	10/218,104		Optical device package for flip-chip mounting	Abandoned
US	60/257,020		FTIR/TIR switch improvements	Expired

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Country	Application Number	Patent Number	Title of Invention	Status
US	10/022,726	6810162	Optical switch assembly with flex plate and method for making	Issued
US	10/954,467	7079725	Optical switch assembly with flex plate and method for making	Issued
US	60/265,191		Optical package having a vertical optoelectronic chip	Expired
US	10/066,299	6917056	Optoelectronic submount having an on-edge optoelectronic device	Issued
US	11/080,372		Optoelectronic submount having an on-edge optoelectronic device	Abandoned
US	60/266,931		Micromachining with both dry and wet etching	Expired
US	10/071,261	6885786	Combined wet and dry etching process for micromachining of crystalline materials	Issued
US	60/299,889		V-groove with tapered depth	Expired
US	10/067,218		V-groove with tapered depth and method for making	Abandoned
US	60/269,011		Structures made by combined etching	Expired

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Country	Application Number	Patent Number	Title of Invention	Status
US	60/269,010		Dry + wet technique for making 2-D fiber arrays	Expired
US	10/076,858	6,964,804	MICROMACHINED STRUCTURES MADE BY COMBINED WET AND DRY ETCHING	Issued
US	10/860,811		Micromachined structures made by combined wet and dry etching	Abandoned
US	11/273,769		Micromachined structures made by combined wet and dry etching	Abandoned
US	60/306,568		V-groove with fiducial for a fiber stop	Expired
US	10/199,476	6907150	Etching process for micromachining crystalline materials and devices fabricated thereby	Issued
US	11/152,671	7198727	Etching process for micromachining materials and devices fabricated thereby	Issued
US	11/152,843		Etching process for micromachining materials and devices fabricated thereby	Abandoned

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Country	Application Number	Patent Number	Title of Invention	Status
PCT	PCT/US02/23177		ETCHING PROCESS FOR MICROMACHINING CRYSTALLINE MATERIALS AND DEVICES FABRICATED THEREBY	Expired
CN	2816376.1		ETCHING PROCESS FOR MICROMACHINING CRYSTALLINE MATERIALS AND DEVICES FABRICATED THEREBY	Pending
EU	2756559.7		ETCHING PROCESS FOR MICROMACHINING CRYSTALLINE MATERIALS AND DEVICES FABRICATED THEREBY	Pending
JP	2003-513732		ETCHING PROCESS FOR MICROMACHINING CRYSTALLINE MATERIALS AND DEVICES FABRICATED THEREBY	Pending
KR	2004-7000893		ETCHING PROCESS FOR MICROMACHINING CRYSTALLINE MATERIALS AND DEVICES FABRICATED THEREBY	Pending
US	60/295,175		Discrete-wavelength tunable laser	Expired

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Country	Application Number	Patent Number	Title of Invention	Status
US	60/472,692		Tunable etalon	Expired
US	60/472,873		Micromachined etalon	Expired
US	60/472,914		Discrete-wavelength tunable laser	Expired
US	10/860,810	7294280	External cavity semiconductor laser and method for fabrication thereof	Issued
US	11/983,843		External cavity semiconductor laser and method for fabrication thereof	Abandoned
CN	200410090310.3		Discrete-wavelength tunable laser	Pending
CN	200710300512.X		Discrete-wavelength tunable laser	Pending
EP	4252984.2	1480302	Discrete-wavelength tunable laser	Issued
EP	7009584.9		Discrete-wavelength tunable laser	Pending
FR	4252984.2	1480302	Discrete-wavelength tunable laser	Issued
DE	4252984.2	1480302	Discrete-wavelength tunable laser	Issued
TW	93114389	1275222	Discrete-wavelength tunable laser	Issued

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Country	Application Number	Patent Number	Title of Invention	Status
UK	4252984.2	1480302	Discrete-wavelength tunable laser	Issued
JP	2004-151886		Discrete-wavelength tunable laser	Pending
US	60/285,907		Solder pads and methods of making a solder pad	Expired
US	10/126,491	6902098	Solder pads and method of making a solder pad	Issued
US	11/925,410	6927492	Solder pads and method of making a solder pad	Issued
US	60/285,906		Optical fiber attached to a substrate	Expired
US	10/126,938	6782182	Optical fiber attached to a substrate	Issued
US	60/300,201		Etching process for micromachining crystalline materials and devices fabricated thereby	Expired
US	60/472,910		Recessed structures made by combined etching	Expired
US	60/472,909		Vertical reflector type optical submount made by combined wet and dry etching	Expired
US	10/860,809	7157016	Etching process for micromachining crystalline materials and devices fabricated thereby	Issued

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Country	Application Number	Patent Number	Title of Invention	Status
US	10/859,589		Etching process for micromachining crystalline materials and devices fabricated thereby	Abandoned
US	10/860,811		Etching process for micromachining crystalline materials and devices fabricated thereby	Abandoned
CN	200410063905.X	200410063905.X	Etching process for micromachining crystalline materials and devices fabricated thereby	Issued
TN	931.14390	1254025	Etching process for micromachining crystalline materials and devices fabricated thereby	Issued
JP	2004-151958		Etching process for micromachining crystalline materials and devices fabricated thereby	Pending
US	60/310,378		Wafer-level testing of silicon optical bench devices	Expired
US	10/214,433	7078671	Silicon optical microbench devices and wafer-level testing thereof	Issued
US	11/446,819	7378646	Optical device package having optical feedthrough	Issued
US	60/318,189		Fiber array having fibers bonded to substrate with solder glass	Expired

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Country	Application Number	Patent Number	Title of Invention	Status
US	10/488,569	7149399	Glass bonded fiber array and method for the fabrication thereof	Issued
PCT	PCT/US02/28763		GLASS BONDED FIBER ARRAY AND METHOD FOR THE FABRICATION THEREOF	Expired
CN	02819852.2	02819852.2	Glass bonded fiber array and method for the fabrication thereof	Issued
EU	2759618.8		Glass bonded fiber array and method for the fabrication thereof	Pending
JP	2003-527469		Glass bonded fiber array and method for the fabrication thereof	Pending
US	60/336,933		Tapered waveguide for coupling between channel waveguide and rib waveguide	Expired
US	60/255,868		Optical waveguide termination with vertical and horizontal mode shaping	Expired
US	60/287,032		Optical waveguide termination with vertical and horizontal mode shaping	Expired
PCT	PCT/01/51497		OPTICAL WAVEGUIDE TERMINATION WITH VERTICAL AND HORIZONTAL MODE SHAPING	Expired

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Country	Application Number	Patent Number	Title of Invention	Status
PCT	PCT/02/38553		OPTICAL WAVEGUIDE TERMINATION WITH VERTICAL AND HORIZONTAL MODE SHAPING	Expired
US	10/498,182	7251406	Optical waveguide termination with vertical and horizontal mode shaping	Issued
JP	2003-551579		Optical waveguide termination with vertical and horizontal mode shaping	Pending
US	60/304,927		2XN fiber array with passive alignment	Expired
US	10/194,954	6865324	Fiber array with passive alignment	Expired
US	60/223,163		Frontside/backside alignment structures for stacked devices	Expired
US	09/923,842	7086134	Alignment apparatus and method for aligning stacked devices	Issued
US	11/500,061	7290321	Alignment apparatus and method for aligning stacked devices	Issued
US	09/903,077	6,737,223	FIBER OPTIC CHIP WITH LENSLET ARRAY AND METHOD OF FABRICATION	Expired
US	10/792,513		Fiber optic chip with lenslet array and method of fabrication	Abandoned

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Country	Application Number	Patent Number	Title of Invention	Status
US	60/325,043		2-D fiber optic array with cross-fibers for alignment	Expired
PCT	PCT/US02/30476		OPTICAL FIBER ARRAY WITH VARIABLE FIBER ANGLE ALIGNMENT AND METHOD FOR THE FABRICATION THEREOF	Expired
US	10/492,281	7024090	Optical fiber array with variable fiber angle alignment and method for the fabrication thereof	Issued
US	10/666,849		Optical fiber array with variable fiber angle alignment and method for the fabrication thereof	Abandoned
JP	2003-531225		OPTICAL FIBER ARRAY WITH VARIABLE FIBER ANGLE ALIGNMENT AND METHOD FOR THE FABRICATION THEREOF	Pending
US	60/337,007		Right angle fiber optic connector	Expired
US	10/494,869	7410304	Optical fiber right angle transition	Issued
PCT	PCT/US02/35982		FIBER OPTIC TERMINATION	Expired
CN	02821649.0	02821649.0	FIBER OPTIC TERMINATION	Issued
JP	2003-543074		FIBER OPTIC TERMINATION	Pending
US	60/533,689		Methods of metallizing non-conductive substrates and metallized non-conductive substrates formed thereby	Expired


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Country	Application Number	Patent Number	Title of Invention	Status
US	11/023,763	7158708	Method of metallizing non-conductive substrates and metallized non-conductive substrates formed thereby	Issued
CN	200410081715.0		Method of metallizing non-conductive substrates and metallized non-conductive substrates formed thereby	Pending
JP	2004-97058		Method of metallizing non-conductive substrates and metallized non-conductive substrates formed thereby	Pending
TN	93140189	1261363	Method of metallizing non-conductive substrates and metallized non-conductive substrates formed thereby	Issued
US	60/686,543		Optical assemblies	Expired
US	11/445,043	7597488	Optical assembly	Issued
US	12/534,446		OPTICAL ASSEMBLIES	Pending
CA	2548857		Optical assembly	Pending
CN	200610092462.6		Optical assembly	Pending
EU	06252810.4		Optical assembly	Pending
JP	2006-150994		Optical assembly	Pending
KR	10-2006-0048439		Optical assembly	Pending
TN	95119101		Optical assembly	Pending
US	60/725,196		Micro-optical device	Expired
US	11/545,908	7352924	Micro-optical device	Issued
CA	2563182		Micro-optical device	Pending
EU	06255223.7		Micro-optical device	Pending
JP	2006-277300		Micro-optical device	Pending

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Country	Application Number	Patent Number	Title of Invention	Status
TN	95137285		Micro-optical device	Pending
US	60/903,490		Electronic device packages and methods of formation	Expired
CN	200810096308.5		Electronic device packages and methods of formation	Pending
EU	08151799.7		Electronic device packages and methods of formation	Pending
JP	2008-042222		Electronic device packages and methods of formation	Pending
KR	10-2008-0016989		Electronic device packages and methods of formation	Pending
TN	97106413		Electronic device packages and methods of formation	Pending
US	12/072,157		Electronic device packages and methods of formation	Pending
US	60/650,948		Micro-optical device and method of making same	Expired
US	11/335,722		Micro-optical device and method of making same	Pending
US	61/008,053		Electronic device package and method of formation	Expired
US	61/009,619		Optoelectronic device packages and methods of formation	Expired
US	61/009,621		Optoelectronic device packages and methods of formation	Expired
US	61/066,945		Prism-coupled optical assemblies and methods of formation	Expired
US	12/338,918		ELECTRONIC DEVICE PACKAGE AND METHOD OF FORMATION	Pending
PCT	PCT/US08/87531		ELECTRONIC DEVICE PACKAGE AND METHOD OF FORMATION	Pending

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Country	Application Number	Patent Number	Title of Invention	Status
CA	2533974		ELECTRONIC DEVICE PACKAGE AND METHOD OF FORMATION	Pending
CN	200610003761.8		ELECTRONIC DEVICE PACKAGE AND METHOD OF FORMATION	Pending
EU	06250481.6		ELECTRONIC DEVICE PACKAGE AND METHOD OF FORMATION	Pending
JP	2006029226		ELECTRONIC DEVICE PACKAGE AND METHOD OF FORMATION	Pending
KR	20060008225		ELECTRONIC DEVICE PACKAGE AND METHOD OF FORMATION	Pending
TN	95103015		ELECTRONIC DEVICE PACKAGE AND METHOD OF FORMATION	Pending

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